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Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2014 [Approved on 25 July 2025, 19:46 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.19%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	57.75%	ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.3%
			Carbon black	1333-86-4	0.9%
			TBBA-epichlorhydrin oligomer Exempt from other regulatory requirements	40039-93-8	2%
			Phenol, polymer with formaldehyde	9003-35-4	7%
			Amorphous quartz	60676-86-0	9.8%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	15%
			Quartz (SiO2) Exempt from other regulatory requirements	14808-60-7	65%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.01%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.08%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	40.97%	SILVER, ELEMENTAL	7440-22-4	0.476%
			COPPER, ELEMENTAL	7440-50-8	0.955%
			Elemental iron	7439-89-6	98.569%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TO-92_H_Pb-Free	Transistor	0.19	g